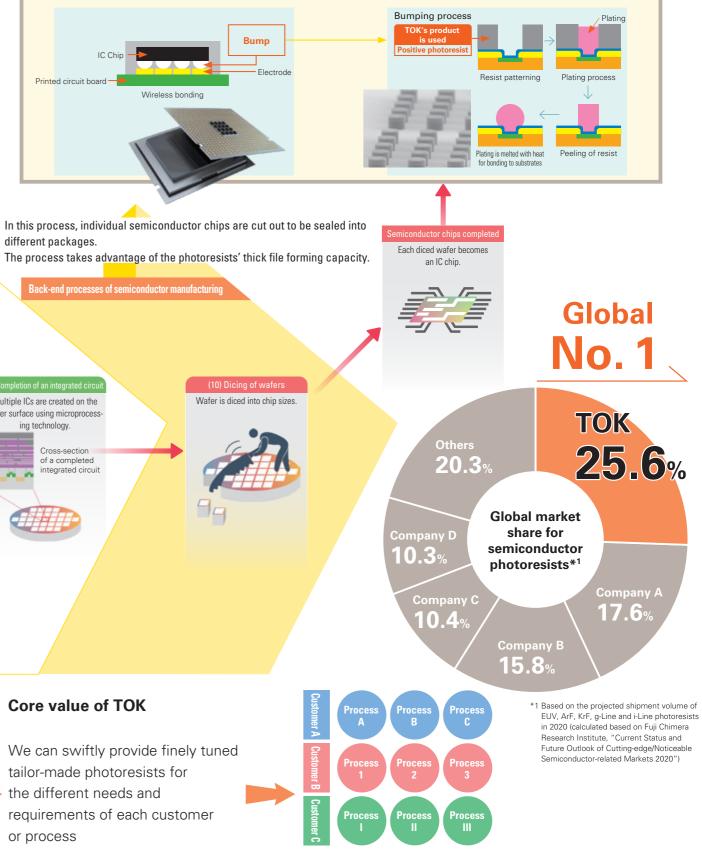
Our Strength

Providing photoresists as growth drivers in both the front-end and back-end processes of semiconductor manufacturing

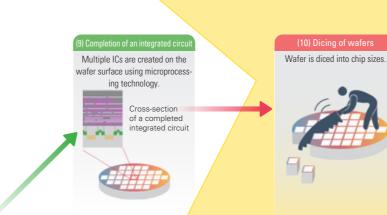
Wireless bonding contributes to downsizing, weight reduction, and higher performance

In this method, projected connection terminals called "bumps" are laid out at the bottom of the IC chip without using fine metal wire and come into direct contact with the printed circuit board for energization. By saving the space for wire connections, the IC chip is directly connected to the printed circuit board, which reduces the connection distance and contributes to downsizing, weight reduction, and higher performance of semiconductor packages.



different packages.





photoresists. Side view

Oxide films

Coat the photosensitive resin

con wafe

(Wafer)

Our Flagship

TOK's Semiconductor Photoresist Business

Process of making integrated circuits on a silicon substrate

Photoresist patterns identical to the

hotomask (circuit design) are formed.

mples of phot

Patterns are formed in the

etching process. (Photoresist

works as a protective film.)

resist patterns

The process uses photoresists' resistance to etching.

A photomask (circuit design) is

transferred to the photoresist.

Front-end processes of semiconductor manufacturing

and producing semiconductor chips.

The top share of the world market for semiconductor photoresists

By honestly continuing efforts to enhance technology and raising the quality levels of products as our management principles since the foundation, TOK has become the world's number one manufacturer of photoresists, which are photosensitive materials indispensable for the manufacture of semiconductors. This section describes the functions, performance, and core value provided by TOK's photoresists in the semiconductor manufacturing process.

Starting point for customer's value creation process

TOK's photoresists create value for customers in their manufacturing process and have a special influence on the quality of customers' output in terms of product quality and yields.

Factors adding value to semiconductor photoresists

Residual photoresist is removed

from the wafer.



A semiconductor field is formed by

coating with an impurity diffusion agent

and baking at high temperatures.

or more details about the use of our

products in the semiconductor manufac-

iring process, please see our website

Aluminum or copper wirings

are formed

ICs are formed by repeating

the processes (1) through (7).

Core value of TOK

tailor-made photoresists for the different needs and requirements of each customer or process

